Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.(currently amended) A method to dissipate heat generated by a coil located within a ~~micro~~-structure, that is on a substrate, comprising:

forming a thermally conductive pedestal that originates at said substrate and extends upwards therefrom; and

forming a layer of thermally conductive material that thermally connects said coil to said substrate through said pedestal, thereby providing an unbroken thermal path between said coil and said substrate.

2.(previously presented) The method of claim 1 wherein said layer of thermally conductive material and said conductive pedestal have a thermal conductivity between 100 and 400 W/m.K.

3. (previously presented) The method of claim 1 wherein said layer of thermally conductive material is selected from the group consisting of copper, tungsten, molybdenum, silicon, ruthenium, rhodium, and iridium.

4. (previously presented) The method of claim 1 wherein said layer of thermally conductive material has a thickness between 1 and 2.5 microns.

5. (previously presented) The method of claim 1 wherein said pedestal has a cross-sectional area that is between 10,000 and 15,000 sq. microns.

6. (previously presented) The method of claim 1 wherein said coil generates heat at a rate between 4 and 15 milliwatts.

7-24. Canceled

25. (currently amended) A heat extractor for a ~~micro~~-structure that includes a coil and a substrate, comprising:

a thermally conductive pedestal that originates at said substrate and extends upwards therefrom; and

a layer of thermally conductive material that thermally connects said pedestal to said coil, thereby providing an unbroken thermal path between said coil and said substrate.

26. (previously presented) The heat extractor described in claim 25 wherein said layer of thermally conductive material and said conductive pedestal have a thermal conductivity between 100 and 400 W/m.K.

27. (previously presented) The heat extractor described in claim 25 wherein said layer of thermally conductive material is selected from the group consisting of copper, tungsten, molybdenum, silicon, ruthenium, rhodium, and iridium.

28. (previously presented) The heat extractor described in claim 25 wherein said layer of thermally conductive material has a thickness between 1 and 2.5 microns.

29. (previously presented) The heat extractor described in claim 25 wherein said pedestal has a cross-sectional area that is between 10,000 and 15,000 sq. microns.